



MODEL: HSS-B20-NP-06 | **DESCRIPTION:** HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- low profile design
- black anodized finish



MODEL

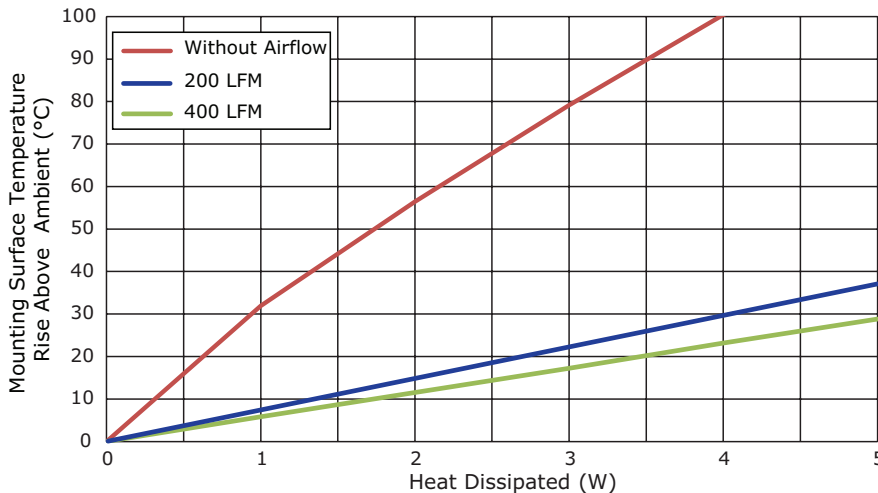
	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSS-B20-NP-06	26.32	31.94	7.51	5.84	2.85

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	31.94	7.51	5.84
2	56.44	14.85	11.53
3	79.15	22.50	17.26
4	100.39	30.12	23.17
5	116.77	37.08	28.81

T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



CUI DEVICES | **MODEL:** HSS-B20-NP-06 | **DESCRIPTION:** HEAT SINK

MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL1050
FINISH	black anodized
THICKNESS	1.2 mm
WEIGHT	1.7 g

